

Product Specification

XBLW SN74HC541

Octal Buffer/Line Driver; 3-state

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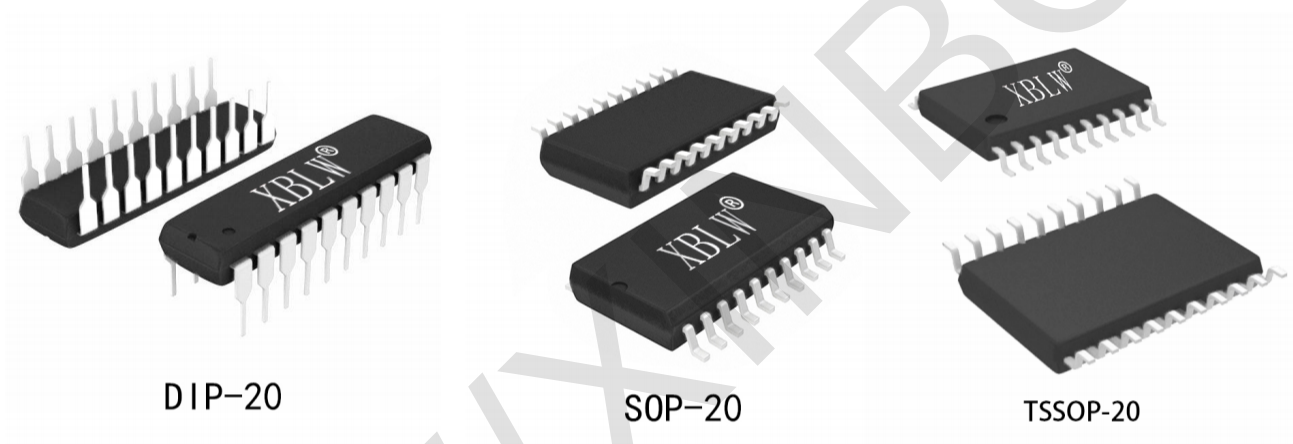


Description

The SN74HC541 is a octal non-inverting buffer/line driver with 3-state outputs. The device features two output enables (OE1 and OE2). A HIGH on OEn causes the outputs to assume a high-impedance OFF-state. Inputs include clamp diodes that enable the use of current limiting resistors to interface inputs to voltages in excess of V_{CC} .

Features

- Non-Inverting outputs
- Specified from -40°C to +125°C
- Packaging information: DIP-20/SOP-20/TSSOP-20



Ordering Information

Product Model	Package Type	Marking	Packing	Packing Qty
XBLW SN74HC541N	DIP-20	74HC541N	Tube	720Pcs/Box
XBLW SN74HC541DTR	SOP-20	74HC541	Tape	2000Pcs/Reel
XBLW SN74HC541TDTR	TSSOP-20	74HC541	Tape	2000Pcs/Reel

Block Diagram

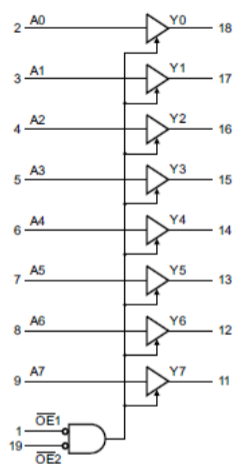


Figure 1. Logic symbol

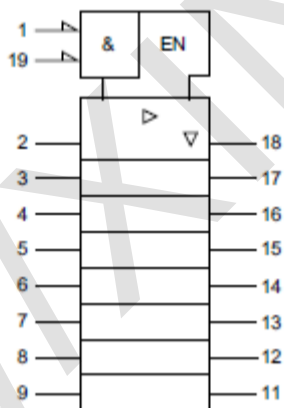


Figure 2. IEC logic symbol

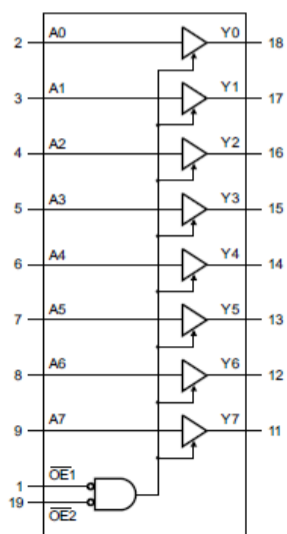


Figure 3. Functional diagram

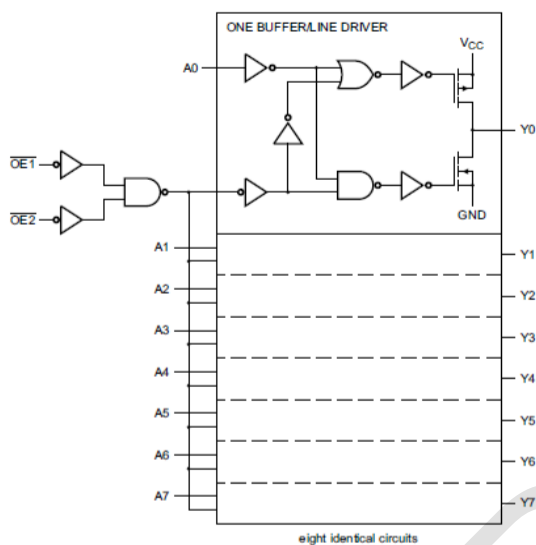
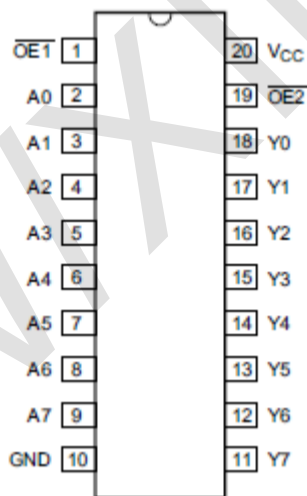


Figure 4. Logic diagram

Pin Configurations



Pin Description

Pin No.	Pin Name	Description
1	$\overline{\text{OE1}}$	output enable input (active LOW)
2	A0	data input
3	A1	data input
4	A2	data input
5	A3	data input
6	A4	data input
7	A5	data input
8	A6	data input
9	A7	data input
10	GND	ground (0V)
11	Y7	data output
12	Y6	data output
13	Y5	data output
14	Y4	data output
15	Y3	data output
16	Y2	data output
17	Y1	data output
18	Y0	data output
19	$\overline{\text{OE2}}$	output enable input (active LOW)
20	V _{CC}	supply voltage

Function Table

Input			Output
$\overline{\text{OE1}}$	$\overline{\text{OE2}}$	A _n	Y _n
L	L	L	L
L	L	H	H
X	H	X	Z
H	X	X	Z

Note: H=HIGH voltage level; L=LOW voltage level; X=don't care; Z=high-impedance OFF-state.

Electrical Parameter

Absolute Maximum Ratings

(Voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	Conditions	Min.	Max.	Unit
supply voltage	V_{CC}	-	-0.5	+7.0	V
input clamping current	I_{IK}	$V_I < -0.5V$ or $V_I > V_{CC}+0.5V$	-	± 20	mA
output clamping current	I_{OK}	$V_O < -0.5V$ or $V_O > V_{CC}+0.5V$	-	± 20	mA
output current	I_O	$-0.5V < V_O < V_{CC}+0.5V$	-	± 35	mA
supply current	I_{CC}	-	-	70	mA
ground current	I_{GND}	-	-70	-	mA
storage temperature	T_{stg}	-	-65	+150	°C
total power dissipation	P_{tot}	-	-	500	mW
Soldering temperature	T_L	10s	DIP	245	°C
			SOP/TSSOP	260	

Recommended Operating Conditions

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
supply voltage	V_{CC}	-	2.0	5.0	6.0	V
input voltage	V_I	-	0	-	V_{CC}	V
output voltage	V_O	-	0	-	V_{CC}	V
input transition rise and fall rate	$\Delta t/\Delta V$	$V_{CC}=2.0V$	-	-	625	ns/V
		$V_{CC}=4.5V$	-	1.67	139	ns/V
		$V_{CC}=6.0V$	-	-	83	ns/V
ambient temperature	T_{amb}	-	-40	-	+125	°C

Electrical Characteristics

DC Characteristics 1

($T_{amb}=25^{\circ}\text{C}$, voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	Conditions		Min.	Typ.	Max.	Unit
HIGH-level input voltage	V_{IH}	$V_{CC}=2.0V$		1.5	1.2	-	V
		$V_{CC}=4.5V$		3.15	2.4	-	V
		$V_{CC}=6.0V$		4.2	3.2	-	V
LOW-level input voltage	V_{IL}	$V_{CC}=2.0V$		-	0.8	0.5	V
		$V_{CC}=4.5V$		-	2.1	1.35	V
		$V_{CC}=6.0V$		-	2.8	1.8	V
HIGH-level output voltage	V_{OH}	$V_I = V_{IH} \text{ or } V_{IL}$	$I_O=-20\mu A; V_{CC}=2.0V$	1.9	2.0	-	V
			$I_O=-20\mu A; V_{CC}=4.5V$	4.4	4.5	-	V
			$I_O=-20\mu A; V_{CC}=6.0V$	5.9	6.0	-	V
			$I_O=-6.0mA; V_{CC}=4.5V$	3.98	4.32	-	V
			$I_O=-7.8mA; V_{CC}=6.0V$	5.48	5.81	-	V
LOW-level output voltage	V_{OL}	$V_I = V_{IH} \text{ or } V_{IL}$	$I_O=20\mu A; V_{CC}=2.0V$	-	0	0.1	V
			$I_O=20\mu A; V_{CC}=4.5V$	-	0	0.1	V
			$I_O=20\mu A; V_{CC}=6.0V$	-	0	0.1	V
			$I_O=6.0mA; V_{CC}=4.5V$	-	0.15	0.26	V
			$I_O=7.8mA; V_{CC}=6.0V$	-	0.16	0.26	V
input leakage current	I_I	$V_I=V_{CC} \text{ or } GND; V_{CC}=6.0V$		-	-	± 1.0	μA
OFF-state output current	I_{OZ}	$V_I=V_{IH} \text{ or } V_{IL}; V_{CC}=6.0V; V_O=V_{CC} \text{ or } GND$		-	-	± 1.0	μA
supply current	I_{CC}	$V_I=V_{CC} \text{ or } GND; I_O=0A; V_{CC}=6.0V$		-	-	8.0	μA
input capacitance	C_i	-		-	3.5	-	pF

DC Characteristics 2

(T_{amb}=-40°C to +85°C, voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
HIGH-level input voltage	V _{IH}	V _{CC} =2.0V	1.5	-	-	V
		V _{CC} =4.5V	3.15	-	-	V
		V _{CC} =6.0V	4.2	-	-	V
LOW-level input voltage	V _{IL}	V _{CC} =2.0V	-	-	0.5	V
		V _{CC} =4.5V	-	-	1.35	V
		V _{CC} =6.0V	-	-	1.8	V
HIGH-level output voltage	V _{OH}	V _I = V _{IH} or V _{IL}	I _O =-20uA; V _{CC} =2.0V	1.9	-	V
			I _O =-20uA; V _{CC} =4.5V	4.4	-	V
			I _O =-20uA; V _{CC} =6.0V	5.9	-	V
			I _O =-6.0mA; V _{CC} =4.5V	3.84	-	V
			I _O =-7.8mA; V _{CC} =6.0V	5.34	-	V
LOW-level output voltage	V _{OL}	V _I = V _{IH} or V _{IL}	I _O =20uA; V _{CC} =2.0V	-	-	0.1
			I _O =20uA; V _{CC} =4.5V	-	-	0.1
			I _O =20uA; V _{CC} =6.0V	-	-	0.1
			I _O =6.0mA; V _{CC} =4.5V	-	-	0.33
			I _O =7.8mA; V _{CC} =6.0V	-	-	0.33
input leakage current	I _I	V _I =V _{CC} or GND; V _{CC} =6.0V	-	-	±1.0	uA
OFF-state output current	I _{OZ}	V _I =V _{IH} or V _{IL} ; V _{CC} =6.0V; V _O =V _{CC} or GND	-	-	±5.0	uA
supply current	I _{CC}	V _I =V _{CC} or GND; I _O =0A; V _{CC} =6.0V	-	-	80	uA

DC Characteristics 3

(T_{amb}=-40°C to +125°C, voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	Conditions		Min.	Typ.	Max.	Unit
HIGH-level input voltage	V _{IH}	V _{CC} =2.0V		1.5	-	-	V
		V _{CC} =4.5V		3.15	-	-	V
		V _{CC} =6.0V		4.2	-	-	V
LOW-level input voltage	V _{IL}	V _{CC} =2.0V		-	-	0.5	V
		V _{CC} =4.5V		-	-	1.35	V
		V _{CC} =6.0V		-	-	1.8	V
HIGH-level output voltage	V _{OH}	V _I = V _{IH} or V _{IL}	I _O =-20uA; V _{CC} =2.0V	1.9	-	-	V
			I _O =-20uA; V _{CC} =4.5V	4.4	-	-	V
			I _O =-20uA; V _{CC} =6.0V	5.9	-	-	V
			I _O =-6.0mA; V _{CC} =4.5V	3.7	-	-	V
			I _O =-7.8mA; V _{CC} =6.0V	5.2	-	-	V
LOW-level output voltage	V _{OL}	V _I = V _{IH} or V _{IL}	I _O =20uA; V _{CC} =2.0V	-	-	0.1	V
			I _O =20uA; V _{CC} =4.5V	-	-	0.1	V
			I _O =20uA; V _{CC} =6.0V	-	-	0.1	V
			I _O =6.0mA; V _{CC} =4.5V	-	-	0.4	V
			I _O =7.8mA; V _{CC} =6.0V	-	-	0.4	V
input leakage current	I _I	V _I =V _{CC} or GND; V _{CC} =6.0V		-	-	±1.0	uA
OFF-state output current	I _{OZ}	V _I =V _{IH} or V _{IL} ; V _{CC} =6.0V; V _O =V _{CC} or GND		-	-	±10	uA
supply current	I _{CC}	V _I =V _{CC} or GND; I _O =0A; V _{CC} =6.0V		-	-	160	uA

AC Characteristics 1

($T_{amb}=25^{\circ}C$, $GND=0V$, $C_L=50pF$, unless otherwise specified.)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
An to Yn propagation delay	t_{pd}	see Figure 6	$V_{CC}=2.0V$	-	33	115 ns
			$V_{CC}=4.5V$	-	12	23 ns
			$V_{CC}=5.0V$; $C_L=15pF$	-	10	- ns
			$V_{CC}=6.0V$	-	10	20 ns
$\overline{O}En$ to Yn enable time	t_{en}	see Figure 7	$V_{CC}=2.0V$	-	55	160 ns
			$V_{CC}=4.5V$	-	20	32 ns
			$V_{CC}=6.0V$	-	16	27 ns
$\overline{O}En$ to Yn disable time	t_{dis}	see Figure 7	$V_{CC}=2.0V$	-	61	160 ns
			$V_{CC}=4.5V$	-	22	32 ns
			$V_{CC}=6.0V$	-	18	27 ns
transition time	t_t	see Figure 6	$V_{CC}=2.0V$	-	14	60 ns
			$V_{CC}=4.5V$	-	5	12 ns
			$V_{CC}=6.0V$	-	4	10 ns
power dissipation capacitance	C_{PD}	per buffer; $V_I=GND$ to V_{CC}	-	37	-	pF

Note:

[1] t_{pd} is the same as t_{PLH} and t_{PHL} .

[2] t_{en} is the same as t_{PZL} and t_{PZH} .

[3] t_{dis} is the same as t_{PLZ} and t_{PHZ} .

[4] t_t is the same as t_{THL} and t_{TLH} .

[5] C_{PD} is used to determine the dynamic power dissipation (P_D in uW).

$P_D=C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o)$ where: f_i =input frequency in MHz;

f_o =output frequency in MHz;

C_L =output load capacitance in pF; V_{CC} =supply voltage in V;

N =number of inputs switching; $\Sigma(C_L \times V_{CC}^2 \times f_o)$ =sum of outputs.

AC Characteristics 2

($T_{amb} = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$, $GND = 0V$, $C_L = 50pF$, unless otherwise specified.)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
An to Yn propagation delay	t_{pd}	see Figure 6	$V_{CC}=2.0V$	-	-	145 ns
			$V_{CC}=4.5V$	-	-	29 ns
			$V_{CC}=6.0V$	-	-	25 ns
$\bar{O}En$ to Yn enable time	t_{en}	see Figure 7	$V_{CC}=2.0V$	-	-	200 ns
			$V_{CC}=4.5V$	-	-	40 ns
			$V_{CC}=6.0V$	-	-	34 ns
$\bar{O}En$ to Yn disable time	t_{dis}	see Figure 7	$V_{CC}=2.0V$	-	-	200 ns
			$V_{CC}=4.5V$	-	-	40 ns
			$V_{CC}=6.0V$	-	-	34 ns
transition time	t_t	see Figure 6	$V_{CC}=2.0V$	-	-	75 ns
			$V_{CC}=4.5V$	-	-	15 ns
			$V_{CC}=6.0V$	-	-	13 ns

Note:

[1] t_{pd} is the same as t_{PLH} and t_{PHL} .

[2] t_{en} is the same as t_{PZL} and t_{PZH} .

[3] t_{dis} is the same as t_{PLZ} and t_{PHZ} .

[4] t_t is the same as t_{THL} and t_{TLH} .

AC Characteristics 3

($T_{amb} = -40^{\circ}\text{C}$ to $+125^{\circ}\text{C}$, $GND = 0V$, $C_L = 50pF$, unless otherwise specified.)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
An to Yn propagation delay	t_{pd}	see Figure 6	$V_{CC}=2.0V$	-	175	ns
			$V_{CC}=4.5V$	-	35	ns
			$V_{CC}=6.0V$	-	30	ns
$\bar{O}En$ to Yn enable time	t_{en}	see Figure 7	$V_{CC}=2.0V$	-	240	ns
			$V_{CC}=4.5V$	-	48	ns
			$V_{CC}=6.0V$	-	41	ns
$\bar{O}En$ to Yn disable time	t_{dis}	see Figure 7	$V_{CC}=2.0V$	-	240	ns
			$V_{CC}=4.5V$	-	48	ns
			$V_{CC}=6.0V$	-	41	ns
transition time	t_t	see Figure 6	$V_{CC}=2.0V$	-	90	ns
			$V_{CC}=4.5V$	-	18	ns
			$V_{CC}=6.0V$	-	15	ns

Note:

[1] t_{pd} is the same as t_{PLH} and t_{PHL} .

[2] t_{en} is the same as t_{PZL} and t_{PZH} .

[3] t_{dis} is the same as t_{PLZ} and t_{PHZ} .

[4] t_t is the same as t_{THL} and t_{TLH} .

Testing Circuit

AC Testing Circuit

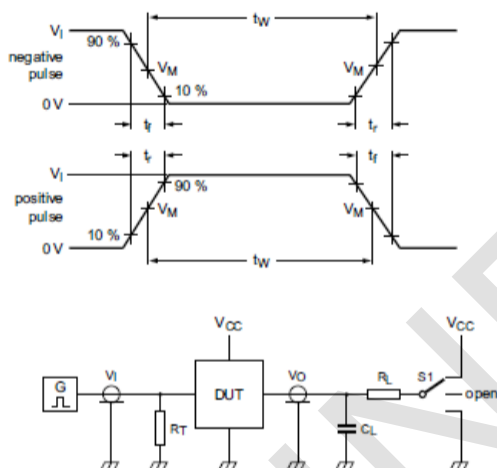


Figure 5. Test circuit for measuring switching times

Definitions for test circuit: R_L =Load resistance.

C_L =Load capacitance including jig and probe capacitance.

R_T =Termination resistance should be equal to the output impedance Z_o of the pulse generator.

S1=Test selection switch.

AC Testing Waveforms

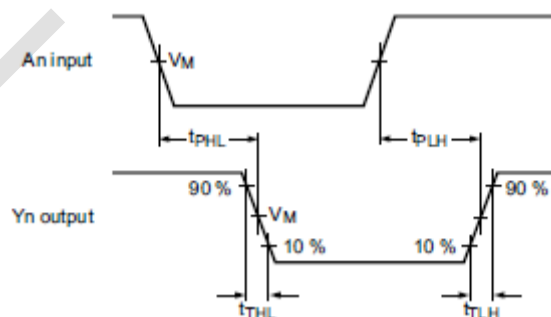


Figure 6. Input to output propagation delays

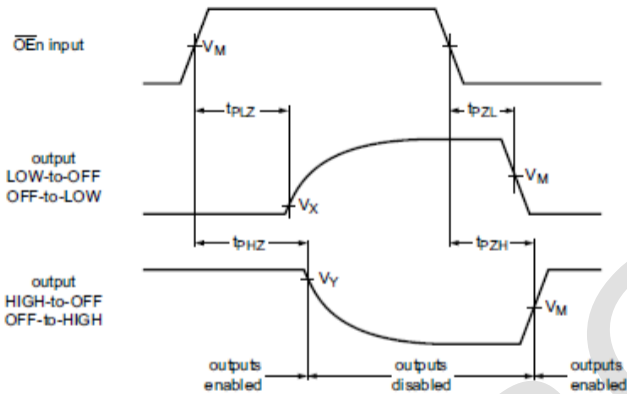


Figure 7. 3-state enable and disable times

Measurement Points

Type	Input	Output		
	V _M	V _M	V _X	V _Y
SN74HC541	0.5×V _{CC}	0.5×V _{CC}	0.1×V _{CC}	0.9×V _{CC}

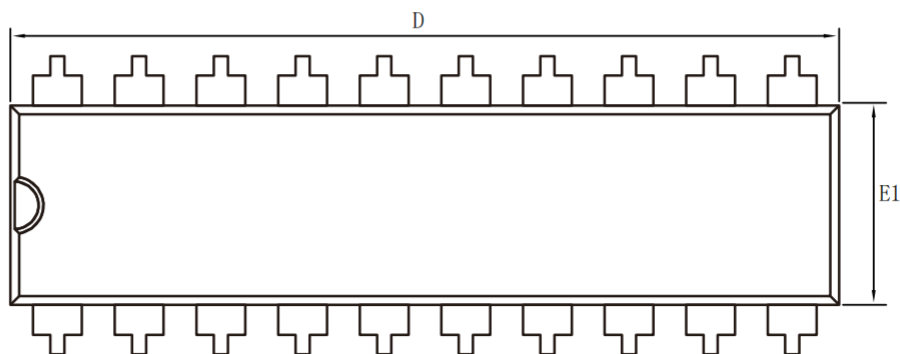
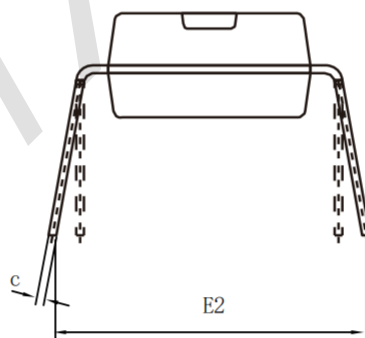
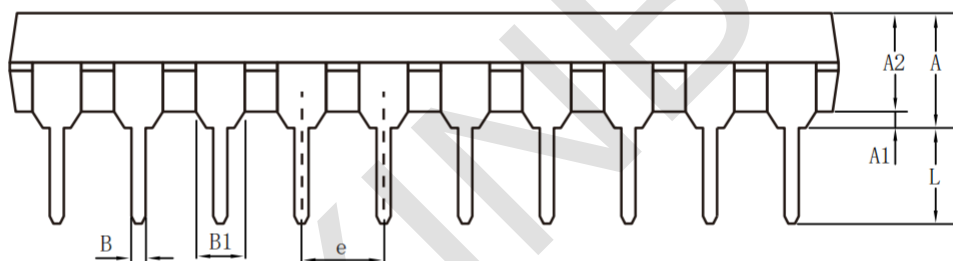
Test Data

Type	Input		Load		S1 position		
	V _I	t _r , t _f	C _L	R _L	t _{PHL} , t _{PLH}	t _{PZH} , t _{PHZ}	t _{PZL} , t _{PLZ}
SN74HC541	V _{CC}	6ns	15pF, 50pF	1kΩ	open	GND	V _{CC}

Package Information

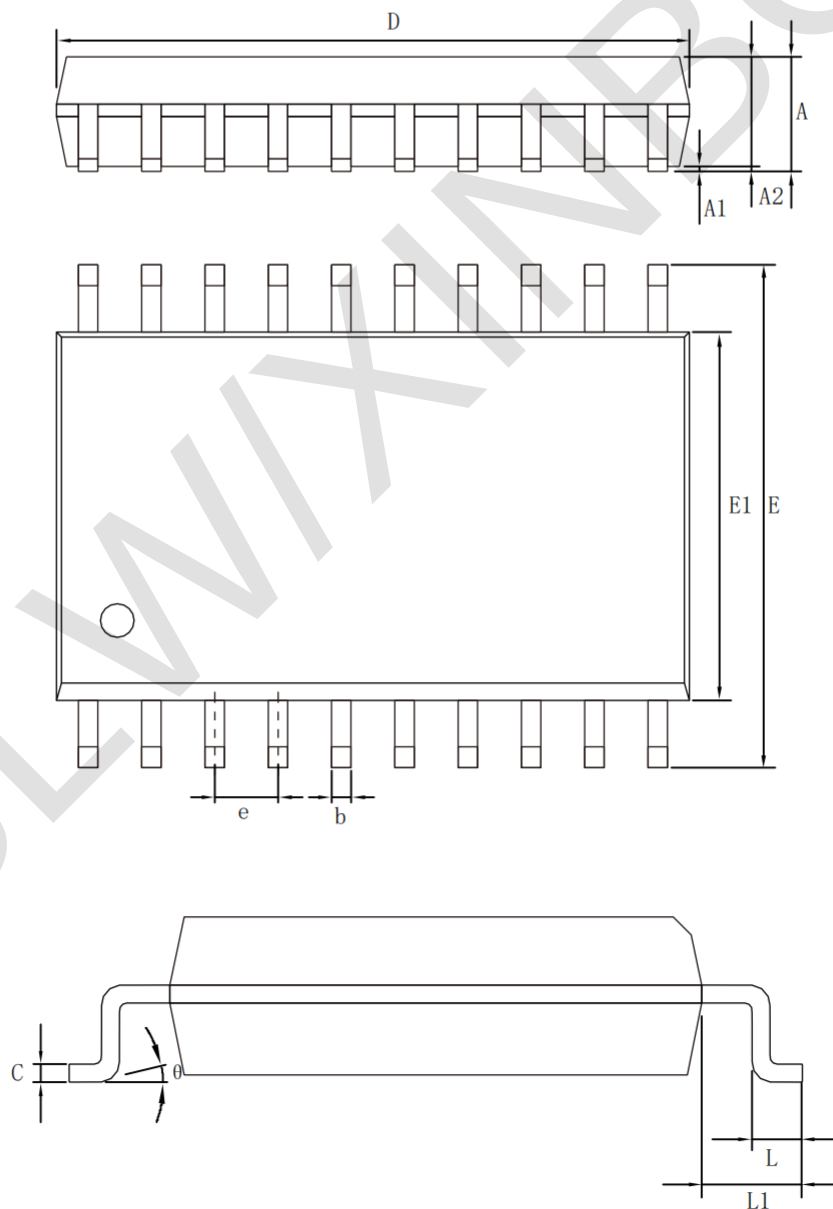
· DIP-20

Symbol	Size		Dimensions In Millimeters		Symbol	Size		Dimensions In Inches	
			Min (mm)	Max (mm)				Min (in)	Max (in)
A			3.600	5.330	A			0.142	0.210
A1			0.510		A1			0.020	
A2			3.200	3.600	A2			0.126	0.142
B			0.360	0.530	B			0.014	0.021
B1			1.52 (BSC)		B1			0.060 (BSC)	
c			0.204	0.360	c			0.008	0.014
D			25.70	26.54	D			1.010	1.040
E1			6.200	6.750	E1			0.244	0.260
E2			7.620	9.300	E2			0.300	0.366
e			2.54 (BSC)		e			0.100 (BSC)	
L			3.000	3.600	L			0.118	0.142



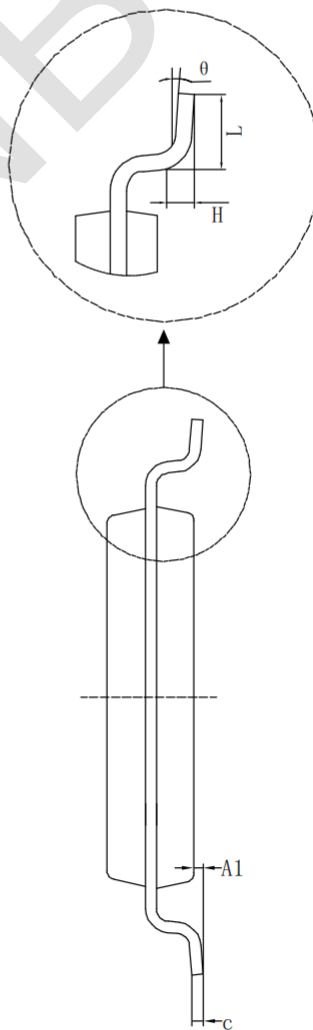
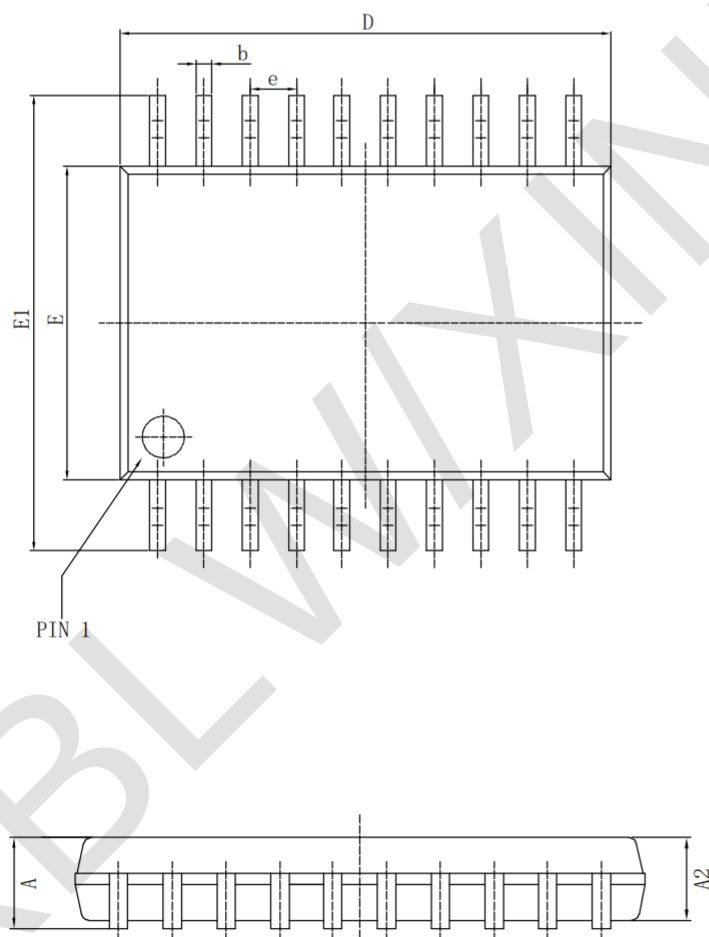
▪ SOP-20

Symbol \ Size	Dimensions In Millimeters		Symbol \ Size	Dimensions In Inches	
	Min(mm)	Max(mm)		Min(in)	Max(in)
A	2.470	2.650	A	0.097	0.104
A1	0.050	0.300	A1	0.002	0.012
A2	2.200	2.440	A2	0.087	0.096
b	0.350	0.500	b	0.014	0.020
c	0.150	0.300	c	0.006	0.012
D	12.54	12.94	D	0.494	0.509
E	10.00	10.60	E	0.394	0.417
E1	7.300	7.700	E1	0.287	0.303
e	1.270 (BSC)		e	0.050 (BSC)	
L	0.400	1.050	L	0.016	0.041
L1	1.300	1.500	L1	0.051	0.059
θ	0°	8°	θ	0°	8°



· TSSOP-20

Size Symbol	Dimensions In Millimeters		Size Symbol	Dimensions In Inches	
	Min(mm)	Max(mm)		Min(in)	Max(in)
D	6.400	6.600	D	0.252	0.259
E	4.300	4.500	E	0.169	0.177
b	0.190	0.300	b	0.007	0.012
c	0.090	0.200	c	0.004	0.008
E1	6.250	6.550	E1	0.246	0.258
A		1.200	A		0.047
A2	0.800	1.000	A2	0.031	0.039
A1	0.050	0.150	A1	0.002	0.006
e	0.65 (BSC)		e	0.026 (BSC)	
L	0.500	0.700	L	0.020	0.028
H	0.25 (TYP)		H	0.01 (TYP)	
θ	1°	7°	θ	1°	7°



Statement

- XBLW reserves the right to modify the product manual without prior notice! Before placing an order, customers need to confirm whether the obtained information is the latest version and verify the completeness of the relevant information.
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